Organic semiconductors with a charge carrier life time of over

2 hours at room temperature.

Yang Liu¹ (刘洋), Roderick. C. I. Mackenzie³, Bin Xu (徐斌)¹, Yajun Gao (高亚军)^{1,2}, Miquel

Gimeno-Fabra³, David Grant³, Paul. H. M. van Loosdrecht^{1,2,4}, and Wenjing Tian (田文晶)¹

1. State Key Laboratory of Supramolecular Structures and Materials, Jilin University, 2699 Qianjin Street, Changchun 130012, China

2. Optical Condensed Matter Physics, Zernike Institute for Advanced Materials, University of Groningen, Nijenborgh 4, 9747AG Groningen, The Netherlands.

3. Faculty of Engineering, The University of Nottingham, University Park, Nottingham, NG7 2RD, UK

4. II. Physikalisches Institut, University of Cologne, Zülpicher Strasse 77, 50937 Cologne, Germany.

S1. Depositing of Al₂O₃ film

Coatings were fabricated by first coating the ITO Teer Coatings UDP 650 closed field unbalanced magnetron-assisted physical vapour deposition (PVD) system of base pressure <3x10-5 Torr. A 57 mm diameter Al_2O_3 target was sputtered using Ar as a working gas at ca. 2 x10⁻³ Torr and 41 sccm. The RF power applied to the target was 100W for a period of 4 hwith an applied negative bias on the substrate of -25 V.

S2. Experimentally determining the permittivity of the insulators



Figure S1: Current transient for a ITO/PS/AI device.



Figure S2: Current transient for a ITO/PMMA/AI device.



Figure S4: Current transient for a $ITO/AI_2O_3/AI$ device.

S3. Encapsulating and not encapsulating the device



Figure S5: Influence of not-encapsulated (red) and encapsulated (black) the device on charge carrier life time.

S4. Full transients from different semiconductors



Figure S6: ITO/SiO2(100nm)/Spiro-OMeTAD(100nm)/AI



Figure S7: ITO/SiO2(100nm)/TAPC(100nm)/AI



Figure S8: ITO/SiO2(100nm)/TPD(100nm)/AI

S4. Modeling

A free copy of the model used to perform the simulations in this paper (figure 7b) can be downloaded at <u>www.opvdm.com</u>. The model is a drift diffusion model which describes recombination using a SRH formalism.

S5. Doping in organic semiconductors

In classical inorganic electronics, one would say a material is pure and undoped if it had a purity

of 99.9999999% (or nine nines purity). The atomic density of silicon is around $5x10^{28}$ atoms/m³, this means in nominally undoped silicon there are $5x10^{19}$ dopant atoms per m³. In contrast, a highly doped inorganic semiconductor has around $1x10^{25}$ dopant atoms per m³. If one now considers organic semiconductors, a material is considered 'pure' if it has a purity of only 99.9%. If we use fullerene for this example, and assume it is a square box with the volume of 1nm * 1nm * 1nm it will have a density of $1x10^{27}$ molecules per m³, if we then assume it is 99.9% pure, we can then calculate that it has a dopant density of $1x10^{24}$ atoms per m³. Thus from these simple calculations, it can be seen that even a 'pure' organic semiconductor is doped almost as much as a highly doped inorganic semiconductor. This simply highlights how contaminated organic semiconductors are when viewed from the inorganic semiconductor stand point and this is the reason why all organic semiconductors studied produced long life times when placed in our device structure.